SYSTRONIC

SYS-CLEAN STC1.0

STENCIL CLEANER

SYS-CLEAN STC1.0 is a water-based cleaning medium to clean SMT stencils at room temperature.
Stencils and misprints are reliably cleaned off solder paste by **SYS-CLEAN STC1.0**.
It can be used in all cleaning systems with spray in air or immersion process as well as for ultrasonic cleaning.

Application

Pollution	Suitability
Solder pastes	✓✓
SMT adhesives and conductive adhesives	✓
Fluxes	✓
Oils	✓

Application Parameters

Parameter	
Application temperature	20°C
Cleaning time approx.	4-6 min.
Rinsing	STC1.0 / DI-Water
Drying	Convection / Compressed Air
Application concentration	Ready to use

Specifications

SYS-CLEAN STC1.0 is supplied as ready to use mixture.

Density	0,9995g/cm³
Boiling point	~100°C
Flashpoint	None
pH value	neutral

Advantages: SYS-CLEAN STC1.0 can be filtert very easily and has optimized drain-off charachteristics wich reduce the consumption and don‘t leave oily residues.
Due to the high loading capacity a particularly cost-effective process is ensured.
Since the media does not separate, an application in the underside cleaning is realized easily.

The addition of defoamers or other additives is not required.

Type of application: Spray in air / spray under immersion / ultrasonic

Safety: Please note the information in the MSDS.

Ecology: SYS-CLEAN STC1.0 is a water based, pH-neutral and bioadegradable substance.
It dries without any residues and thus doesn‘t need water rinsing. No waste water will accure.

Disposal: If required, we will take back used medium and undertake the disposal for you.

Availability: SYS-CLEAN STC1.0 is available in pack sizes of 5, 25 or 200 liters.

ALL COMPONENTS REACH COMPLIANT
Registration, Evaluation and Authorisation of Chemicals

The product is free of questionable ingredients in accordance with the SIN & SVHC lists

WEEE · RoHS · COMPLIANT

100% compliant with the EU RoHS directive 1 & 2, WEEE